

#### NCE N-Channel Enhancement Mode Power MOSFET

#### **Description**

The NCE0205IA uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

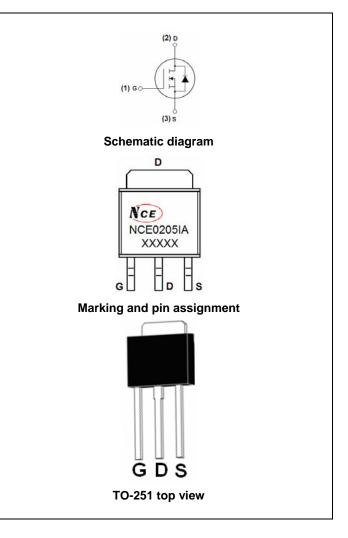
#### **General Features**

- V<sub>DS</sub> = 200V,I<sub>D</sub> =5A
- $R_{DS(ON)} < 580 m\Omega$  @  $V_{GS}$ =10V (Typ:520m $\Omega$ )

   High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation

## **Application**

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply



#### **Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE0205IA	NCE0205IA	TO-251	-	-	-

#### Absolute Maximum Ratings (T<sub>4</sub>=25 ℃unless otherwise noted)

Albertate maximum raumge (TA-20 Cumose cumo metal)					
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V <sub>DS</sub>	200	V		
Gate-Source Voltage	V <sub>GS</sub>	±20	V		
Drain Current-Continuous	I <sub>D</sub>	5	А		
Drain Current-Pulsed (Note 1)	I <sub>DM</sub>	20	А		
Maximum Power Dissipation	P <sub>D</sub>	30	W		
Operating Junction and Storage Temperature Range	$T_{J}$ , $T_{STG}$	-55 To 150	$^{\circ}\!\mathbb{C}$		

#### **Thermal Characteristic**

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	4.17	°C/W

# Electrical Characteristics ( $T_A$ =25 $^{\circ}$ C unless otherwise noted)

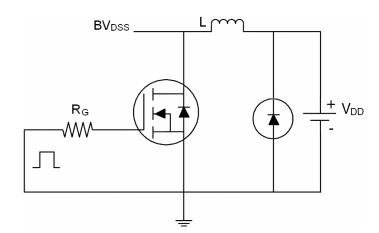
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	- June	Containen		.,,,,	111021	<b>O</b>
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	200	_	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =200V,V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	_	-	±100	nA
On Characteristics (Note 3)	1		I	I	I	I
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ , $I_{D}=250\mu A$	1.2	1.7	2.5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =2A	-	520	580	mΩ
Forward Transconductance	<b>9</b> FS	V <sub>DS</sub> =15V,I <sub>D</sub> =2A	-	8	-	S
Dynamic Characteristics (Note4)	1		1	l.		·
Input Capacitance	C <sub>lss</sub>		-	580	-	PF
Output Capacitance	C <sub>oss</sub>	$V_{DS}$ =25V, $V_{GS}$ =0V,	-	90	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.0MHz	-	3	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>		-	10	-	nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =100V, $R_L$ =15 $\Omega$	-	12	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =10 $V$ , $R_{G}$ =2.5 $\Omega$	-	15	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	15	-	nS
Total Gate Charge	Qg	V <sub>DS</sub> =100V,I <sub>D</sub> =2A, V <sub>GS</sub> =10V	-	12		nC
Gate-Source Charge	Q <sub>gs</sub>		-	2.5	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	vGS-10v	-	3.8	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =2A	-	-	1.2	V
Diode Forward Current (Note 2)	Is		-	-	5	Α

#### Notes:

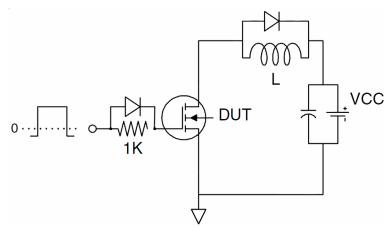
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production

### **Test Circuit**

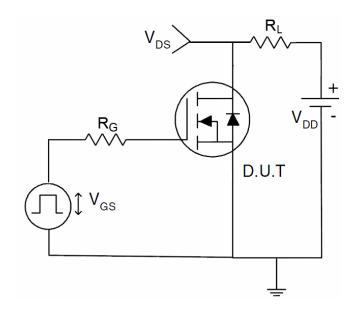
1) E<sub>AS</sub> test circuit



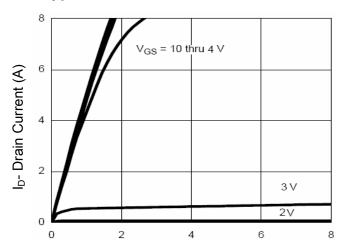
# 2) Gate charge test circuit



### 3) Switch Time Test Circuit

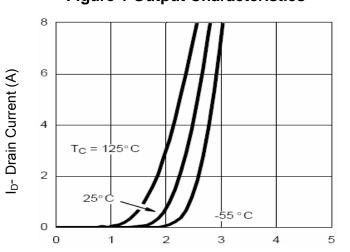


# **Typical Electrical and Thermal Characteristics (Curves)**



Vds Drain-Source Voltage (V)

Figure 1 Output Characteristics



Vgs Gate-Source Voltage (V)
Figure 2 Transfer Characteristics

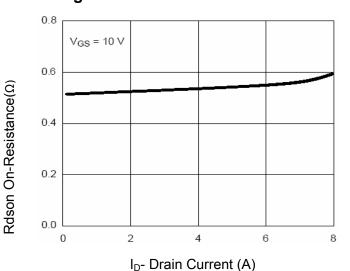
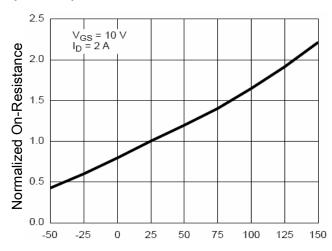


Figure 3 Rdson- Drain Current



 $T_J$ -Junction Temperature (°C) **Figure 4 Rdson-JunctionTemperature** 

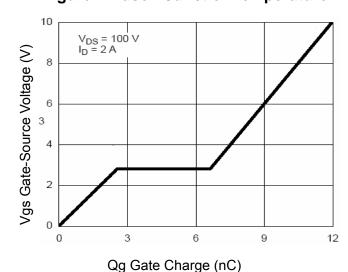


Figure 5 Gate Charge

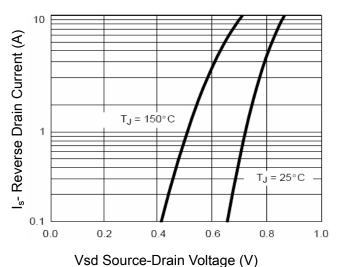


Figure 6 Source- Drain Diode Forward

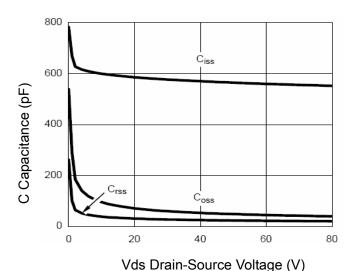


Figure 7 Capacitance vs Vds

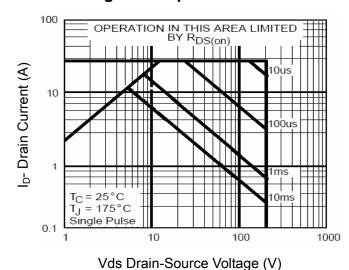
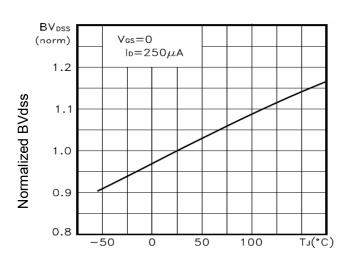
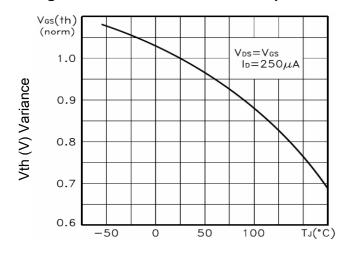


Figure 8 Safe Operation Area



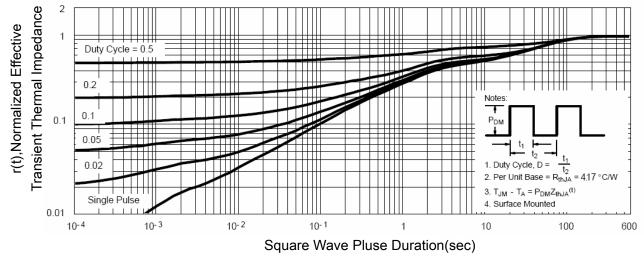
 $T_J$ -Junction Temperature( ${}^{\circ}\mathbb{C}$ )

## Figure 9 BV<sub>DSS</sub> vs Junction Temperature



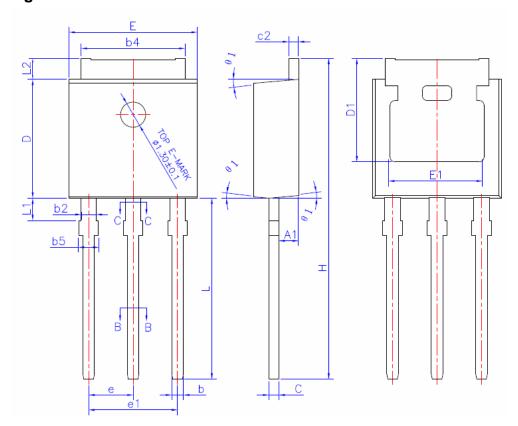
T<sub>J</sub>-Junction Temperature(°C)

Figure 10 V<sub>GS(th)</sub> vs Junction Temperature



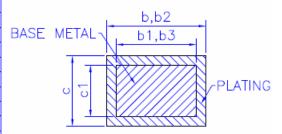
**Figure 11 Normalized Maximum Transient Thermal Impedance** 

# **TO-251 Package Information**



# 

SYMBOL	MIN NO		MAX		
Α	2,20	2.30	2,35		
A1	0.90	1.01	1.10		
b	0.56		0.69		
b1	0.55	0.60	0.65		
b2	0.77		0,90		
b3	0.76	0.81	0.86		
b4	5,23	5,33	5,43		
b5			1.05		
С	0.46		0,59		
c1	0.45	0,51	0.55		
c2	0.46		0.59		
D	6.00	6.10	6.20		
D1	5.20		_		
E	6,50	6,60	6,70		
E1	4.60	4.83	5.00		
e	2,24	2,29	2,34		
e1	4.47	4.57	4.67		
Н	16,18	16,48	16,78		
L	9.00	9.30	9.60		
L1	0.95	1.16	1.35		
L2	0.90	1.08	1,25		
θ1	3°	5°	7°		
θ2	1°	3°	5°		





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